

Line Number	Hits (Item ID, Text)	DB	Time stamp
1	218 (traces and pads)	USPAT; US-PGPUB; EPC; JPO; DEFWENT; IBM_TDB	2003/03/17 12:22
2	219 (traces and pads)	USPAT; US-PGPUB; EPC; JPO; DEFWENT; IBM_TDB	2003/03/17 12:23
3	243 (traces and pads) and solder	USPAT; US-PGPUB; EPC; JPO; DEFWENT; IBM_TDB	2003/03/17 12:23
4	210 (substrate board carrier pcb cb pb) and (traces and pads) and solder	USPAT; US-PGPUB; EPC; JPO; DEFWENT; IBM_TDB	2003/03/17 12:24
5	239 (substrate board carrier pcb cb pb) and (traces and pads) and solder (and inactive active)	USPAT; US-PGPUB; EPC; JPO; DEFWENT; IBM_TDB	2003/03/17 12:31
6	210 (substrate board carrier pcb cb pb) and (traces and pads) and solder (and inactive and active)	USPAT; US-PGPUB; EPC; JPO; DEFWENT; IBM_TDB	2003/03/17 12:48
7	218 (substrate board carrier pcb cb pb) and (traces and pads) and solder (and inactive active) not (substrate board carrier pcb cb pb) and (traces and pads) and solder (and inactive and active)	USPAT; US-PGPUB; EPC; JPO; DEFWENT; IBM_TDB	2003/03/17 12:48